Microchip Technology - AT89LS8252-12AI Datasheet

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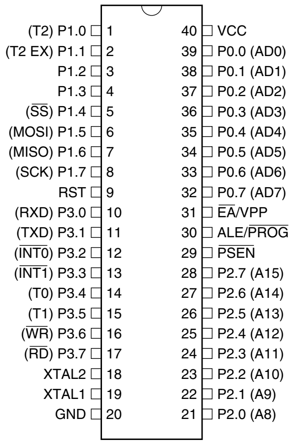
Applications of "Embedded - Microcontrollers"

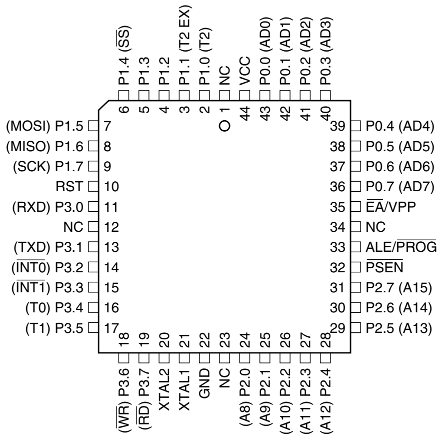
Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	12MHz
Connectivity	SPI, UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	2K x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at89ls8252-12ai

Pin Configurations

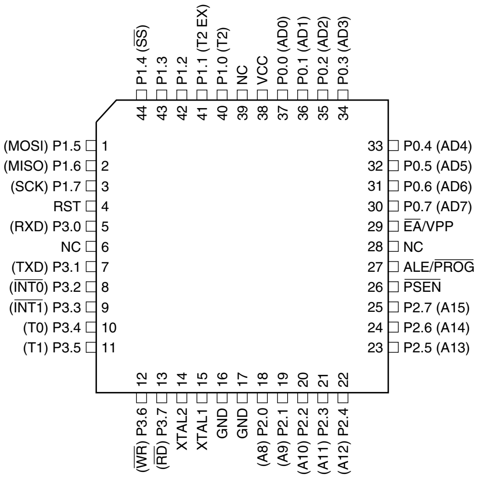
PDIP



PLCC



TQFP



Pin Description

V_{CC}

Supply voltage.

GND

Ground.

Port 0

Port 0 is an 8-bit open drain bidirectional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pullups.

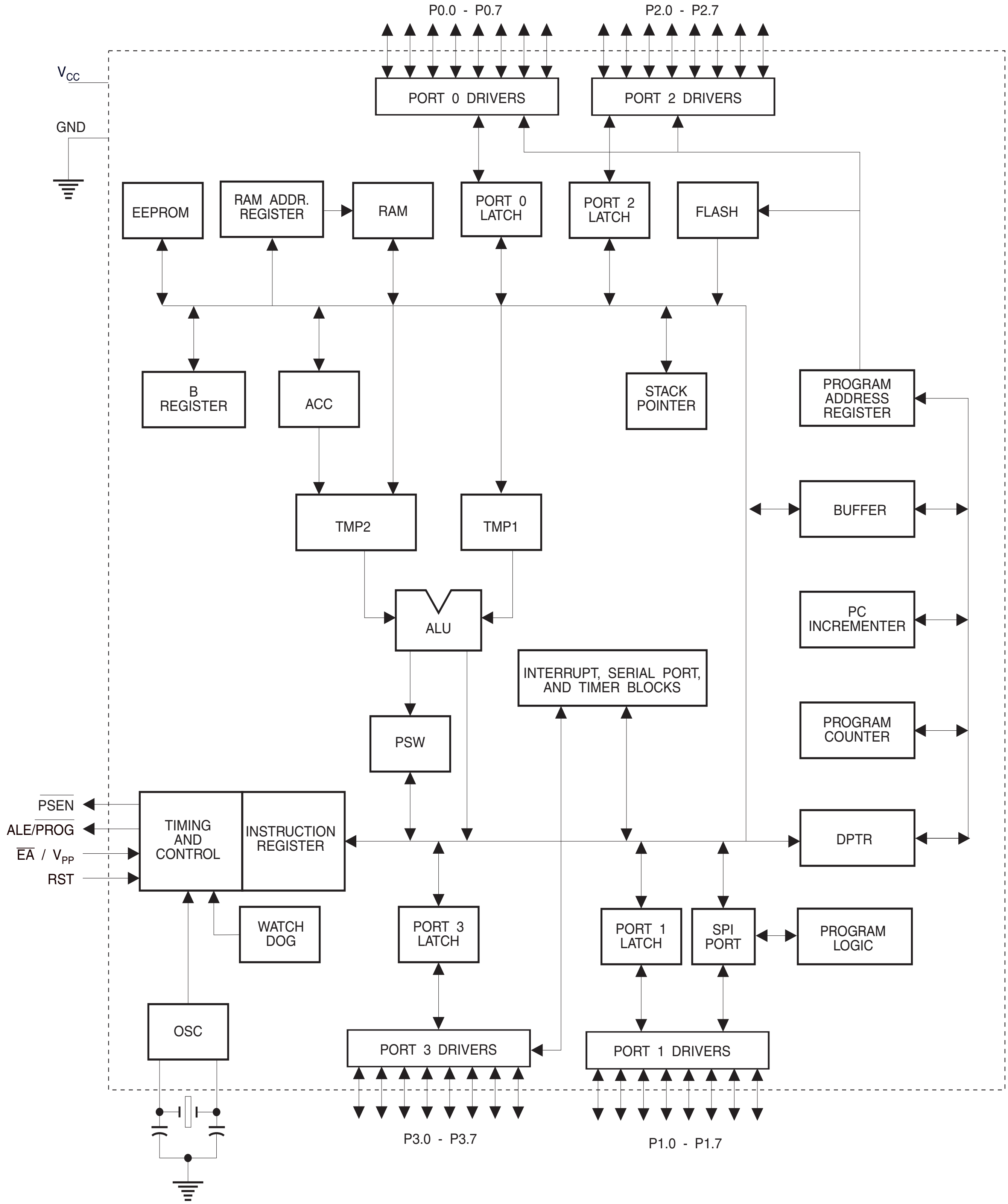
Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. External pullups are required during program verification.

Port 1

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Some Port 1 pins provide additional functions. P1.0 and P1.1 can be configured to be the timer/counter 2 external count input (P1.0/T2) and the timer/counter 2 trigger input (P1.1/T2EX), respectively.

Block Diagram



Pin Description

Furthermore, P1.4, P1.5, P1.6, and P1.7 can be configured as the SPI slave port select, data input/output and shift clock input/output pins as shown in the following table.

Port Pin	Alternate Functions
P1.0	T2 (external count input to Timer/Counter 2), clock-out
P1.1	T2EX (Timer/Counter 2 capture/reload trigger and direction control)
P1.4	$\overline{\text{SS}}$ (Slave port select input)
P1.5	MOSI (Master data output, slave data input pin for SPI channel)
P1.6	MISO (Master data input, slave data output pin for SPI channel)
P1.7	SCK (Master clock output, slave clock input pin for SPI channel)

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port 2

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pullups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pullups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

Port 3

Port 3 is an 8 bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pullups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features of the AT89LS8252, as shown in the following table.

Port 3 also receives some control signals for Flash programming and verification.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{\text{INT0}}$ (external interrupt 0)
P3.3	$\overline{\text{INT1}}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{\text{WR}}$ (external data memory write strobe)
P3.7	$\overline{\text{RD}}$ (external data memory read strobe)

RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

ALE/$\overline{\text{PROG}}$

Address Latch Enable is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ($\overline{\text{PROG}}$) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

$\overline{\text{PSEN}}$

Program Store Enable is the read strobe to external program memory.

When the AT89LS8252 is executing code from external program memory, $\overline{\text{PSEN}}$ is activated twice each machine cycle, except that two $\overline{\text{PSEN}}$ activations are skipped during each access to external data memory.

$\overline{\text{EA}}$/V_{PP}

External Access Enable. $\overline{\text{EA}}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{\text{EA}}$ will be internally latched on reset.

$\overline{\text{EA}}$ should be strapped to V_{CC} for internal program executions. This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming when 12-volt programming is selected.

XTAL1
Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

XTAL2
Output from the inverting oscillator amplifier.

Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

Table 1. AT89LS8252 SFR Map and Reset Values

0F8H									0FFH
0F0H	B 00000000								0F7H
0E8H									0EFH
0E0H	ACC 00000000								0E7H
0D8H									0DFH
0D0H	PSW 00000000					SPCR 000001XX			0D7H
0C8H	T2CON 00000000	T2MOD XXXXXX00	RCAP2L 00000000	RCAP2H 00000000	TL2 00000000	TH2 00000000			0CFH
0C0H									0C7H
0B8H	IP XX000000								0BFH
0B0H	P3 11111111								0B7H
0A8H	IE 0X000000		SPSR 00XXXXXX						0AFH
0A0H	P2 11111111								0A7H
98H	SCON 00000000	SBUF XXXXXXXX							9FH
90H	P1 11111111						WMCON 00000010		97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000			8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000	SPDR XXXXXXXX	PCON 0XXX0000	87H

Dual Data Pointer Registers To facilitate accessing both internal EEPROM and external data memory, two banks of 16 bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR WMCON selects DP0 and DPS = 1 selects DP1. The user should always initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag The Power Off Flag (POF) is located at bit_4 (PCON.4) in the PCON SFR. POF is set to “1” during power up. It can be set and reset under software control and is not affected by RESET.

Table 3. WMCON—Watchdog and Memory Control Register

WMCON Address = 96HReset Value = 0000 0010B

	PS2	PS1	PS0	EEMWE	EEMEN	DPS	WDTRST	WDTEN
Bit	7	6	5	4	3	2	1	0

Symbol	Function
PS2 PS1 PS0	Prescaler Bits for the Watchdog Timer. When all three bits are set to “0”, the watchdog timer has a nominal period of 16 ms. When all three bits are set to “1”, the nominal period is 2048 ms.
EEMWE	EEPROM Data Memory Write Enable Bit. Set this bit to “1” before initiating byte write to on-chip EEPROM with the MOVX instruction. User software should set this bit to “0” after EEPROM write is completed.
EEMEN	Internal EEPROM Access Enable. When EEMEN = 1, the MOVX instruction with DPTR will access on-chip EEPROM instead of external data memory. When EEMEN = 0, MOVX with DPTR accesses external data memory.
DPS	Data Pointer Register Select. DPS = 0 selects the first bank of Data Pointer Register, DP0, and DPS = 1 selects the second bank, DP1
WDTRST RDY/ $\overline{\text{BSY}}$	Watchdog Timer Reset and EEPROM Ready/$\overline{\text{Busy}}$ Flag. Each time this bit is set to “1” by user software, a pulse is generated to reset the watchdog timer. The WDTRST bit is then automatically reset to “0” in the next instruction cycle. The WDTRST bit is Write-Only. This bit also serves as the RDY/$\overline{\text{BSY}}$ flag in a Read-Only mode during EEPROM write. RDY/$\overline{\text{BSY}}$ = 1 means that the EEPROM is ready to be programmed. While programming operations are being executed, the RDY/$\overline{\text{BSY}}$ bit equals “0” and is automatically reset to “1” when programming is completed.
WDTEN	Watchdog Timer Enable Bit. WDTEN = 1 enables the watchdog timer and WDTEN = 0 disables the watchdog timer.

Table 4. SPCR—SPI Control Register

SPCR Address = D5HReset Value = 0000 01XXB

	SPIE	SPE	DORD	MSTR	CPOL	CPHA	SPR1	SPR0
Bit	7	6	5	4	3	2	1	0

Symbol	Function
SPIE	SPI Interrupt Enable. This bit, in conjunction with the ES bit in the IE register, enables SPI interrupts: SPIE = 1 and ES = 1 enable SPI interrupts. SPIE = 0 disables SPI interrupts.
SPE	SPI Enable. SPI = 1 enables the SPI channel and connects $\overline{SS}$, MOSI, MISO and SCK to pins P1.4, P1.5, P1.6, and P1.7. SPI = 0 disables the SPI channel.
DORD	Data Order. DORD = 1 selects LSB first data transmission. DORD = 0 selects MSB first data transmission.
MSTR	Master/Slave Select. MSTR = 1 selects Master SPI mode. MSTR = 0 selects Slave SPI mode.
CPOL	Clock Polarity. When CPOL = 1, SCK is high when idle. When CPOL = 0, SCK of the master device is low when not transmitting. Please refer to figure on SPI Clock Phase and Polarity Control.
CPHA	Clock Phase. The CPHA bit together with the CPOL bit controls the clock and data relationship between master and slave. Please refer to figure on SPI Clock Phase and Polarity Control.
SPR0 SPR1	SPI Clock Rate Select. These two bits control the SCK rate of the device configured as master. SPR1 and SPR0 have no effect on the slave. The relationship between SCK and the oscillator frequency, $F_{OSC.}$, is as follows: SPR1SPR0SCK = $F_{OSC.}$ divided by 0 0 4 0 116 1 064 1 1128

Table 5. SPSR—SPI Status Register

SPSR Address = AAHReset Value = 00XX XXXXB

	SPIF	WCOL	—	—	—	—	—	—
Bit	7	6	5	4	3	2	1	0

Symbol	Function
SPIF	SPI Interrupt Flag. When a serial transfer is complete, the SPIF bit is set and an interrupt is generated if SPIE = 1 and ES = 1. The SPIF bit is cleared by reading the SPI status register with SPIF and WCOL bits set, and then accessing the SPI data register.
WCOL	Write Collision Flag. The WCOL bit is set if the SPI data register is written during a data transfer. During data transfer, the result of reading the SPDR register may be incorrect, and writing to it has no effect. The WCOL bit (and the SPIF bit) are cleared by reading the SPI status register with SPIF and WCOL set, and then accessing the SPI data register.

Timer 0 and 1

Timer 0 and Timer 1 in the AT89LS8252 operate the same way as Timer 0 and Timer 1 in the AT89C51, AT89C52 and AT89C55. For further information, see the October 1995 Microcontroller Data Book, page 2-45, section titled, “Timer/Counters.”

Timer 2

Timer 2 is a 16 bit Timer/Counter that can operate as either a timer or an event counter. The type of operation is selected by bit C/$\overline{T2}$ in the SFR T2CON (shown in Table 2). Timer 2 has three operating modes: capture, auto-reload (up or down counting), and baud rate generator. The modes are selected by bits in T2CON, as shown in Table 8.

Timer 2 consists of two 8-bit registers, TH2 and TL2. In the Timer function, the TL2 register is incremented every machine cycle. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

In the Counter function, the register is incremented in response to a 1-to-0 transition at its corresponding external input pin, T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected. Since two machine cycles (24 oscillator periods) are required to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. To ensure that a given level is sampled at least once before it changes, the level should be held for at least one full machine cycle.

Table 8. Timer 2 Operating Modes

RCLK + TCLK	CP/$\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-Reload
0	1	1	16-bit Capture
1	X	1	Baud Rate Generator
X	X	0	(Off)

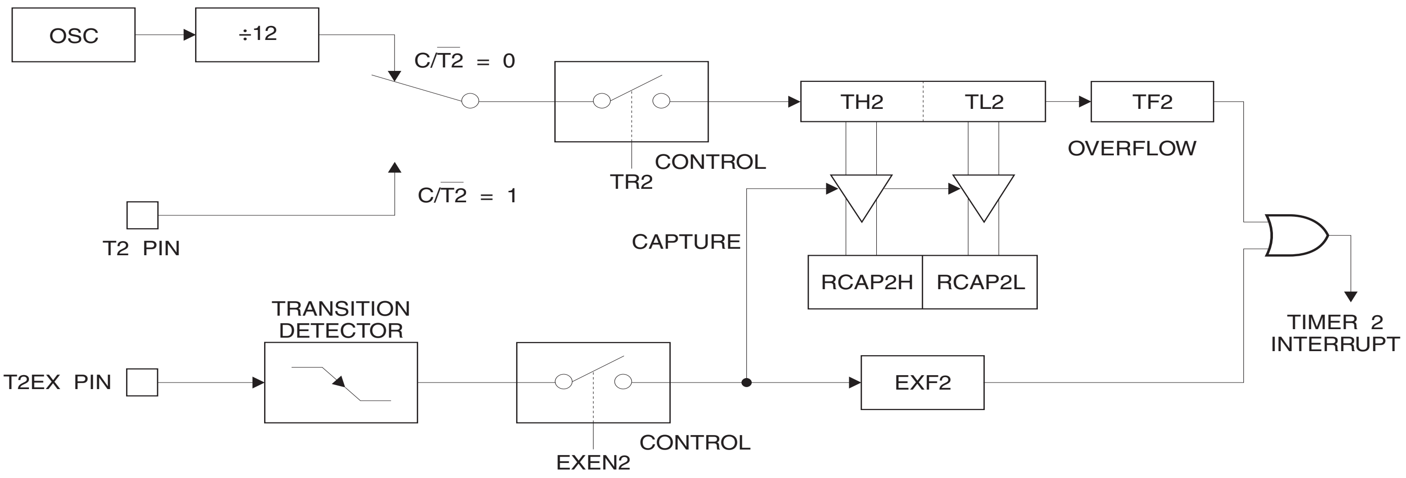
Capture Mode

In the capture mode, two options are selected by bit EXEN2 in T2CON. If EXEN2 = 0, Timer 2 is a 16 bit timer or counter which upon overflow sets bit TF2 in T2CON. This bit can then be used to generate an interrupt. If EXEN2 = 1, Timer 2 performs the same operation, but a 1-to-0 transition at external input T2EX also causes the current value in TH2 and TL2 to be captured into RCAP2H and RCAP2L, respectively. In addition, the transition at T2EX causes bit EXF2 in T2CON to be set. The EXF2 bit, like TF2, can generate an interrupt. The capture mode is illustrated in Figure 1.

Auto-Reload (Up or Down Counter)

Timer 2 can be programmed to count up or down when configured in its 16 bit auto-reload mode. This feature is invoked by the DCEN (Down Counter Enable) bit located in the SFR T2MOD (see Table 9). Upon reset, the DCEN bit is set to 0 so that timer 2 will default to count up. When DCEN is set, Timer 2 can count up or down, depending on the value of the T2EX pin.

Figure 1. Timer 2 in Capture Mode



Programmable Clock Out

A 50% duty cycle clock can be programmed to come out on P1.0, as shown in Figure 5. This pin, besides being a regular I/0 pin, has two alternate functions. It can be programmed to input the external clock for Timer/Counter 2 or to output a 50% duty cycle clock ranging from 61 Hz to 3 MHz at a 12 MHz operating frequency.

To configure the Timer/Counter 2 as a clock generator, bit $C/\overline{T2}$ (T2CON.1) must be cleared and bit T2OE (T2MOD.1) must be set. Bit TR2 (T2CON.2) starts and stops the timer.

The clock-out frequency depends on the oscillator frequency and the reload value of Timer 2 capture registers (RCAP2H, RCAP2L), as shown in the following equation.

$$\text{Clock-Out Frequency} = \frac{\text{Oscillator Frequency}}{4 \times [65536 - (\text{RCAP2H,RCAP2L})]}$$

In the clock-out mode, Timer 2 rollovers will not generate an interrupt. This behavior is similar to when Timer 2 is used as a baud-rate generator. It is possible to use Timer 2 as a baud-rate generator and a clock generator simultaneously. Note, however, that the baud-rate and clock-out frequencies cannot be determined independently from one another since they both use RCAP2H and RCAP2L.

UART

The UART in the AT89LS8252 operates the same way as the UART in the AT89C51, AT89C52 and AT89C55. For further information, see the October 1995 Atmel Microcontroller Data Book, page 2-49, section titled, “Serial Interface.”

Serial Peripheral Interface

The serial peripheral interface (SPI) allows high-speed synchronous data transfer between the AT89LS8252 and peripheral devices or between several AT89LS8252 devices. The AT89LS8252 SPI features include the following:

- Full-Duplex, 3-Wire Synchronous Data Transfer
- Master or Slave Operation
- 1.5-MHz Bit Frequency (max.)
- LSB First or MSB First Data Transfer
- Four Programmable Bit Rates
- End of Transmission Interrupt Flag
- Write Collision Flag Protection
- Wakeup from Idle Mode (Slave Mode Only)

Figure 6. SPI Block Diagram

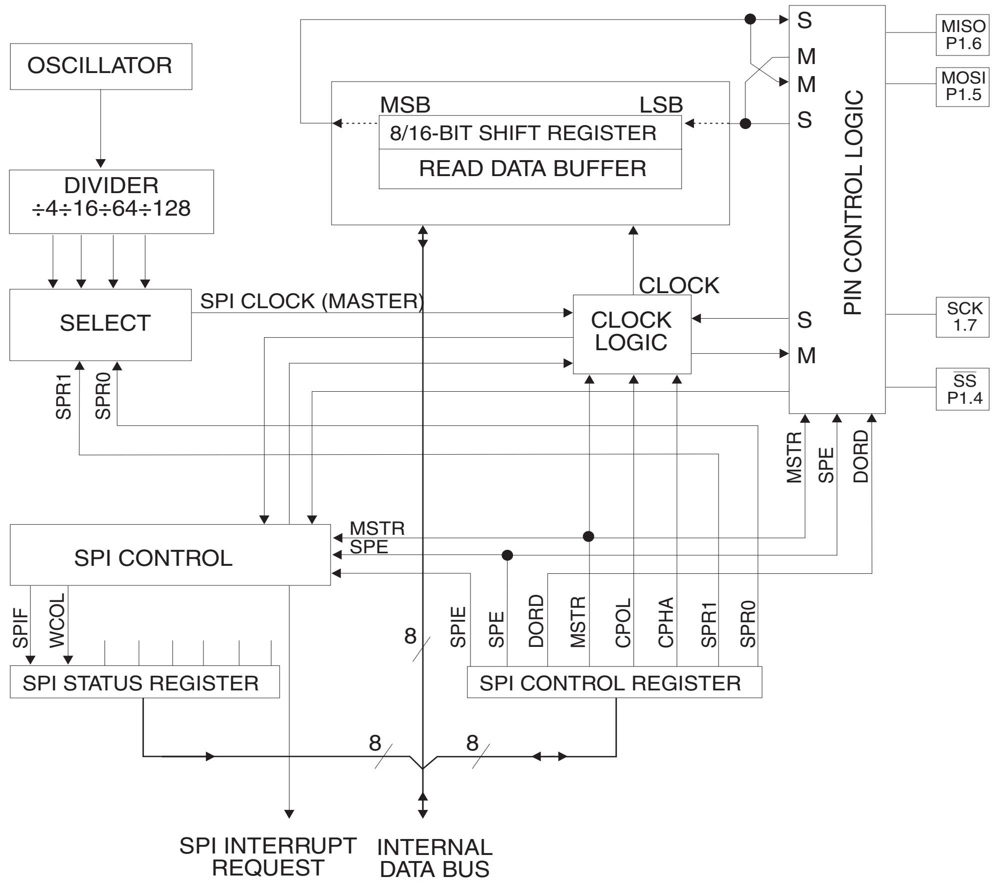
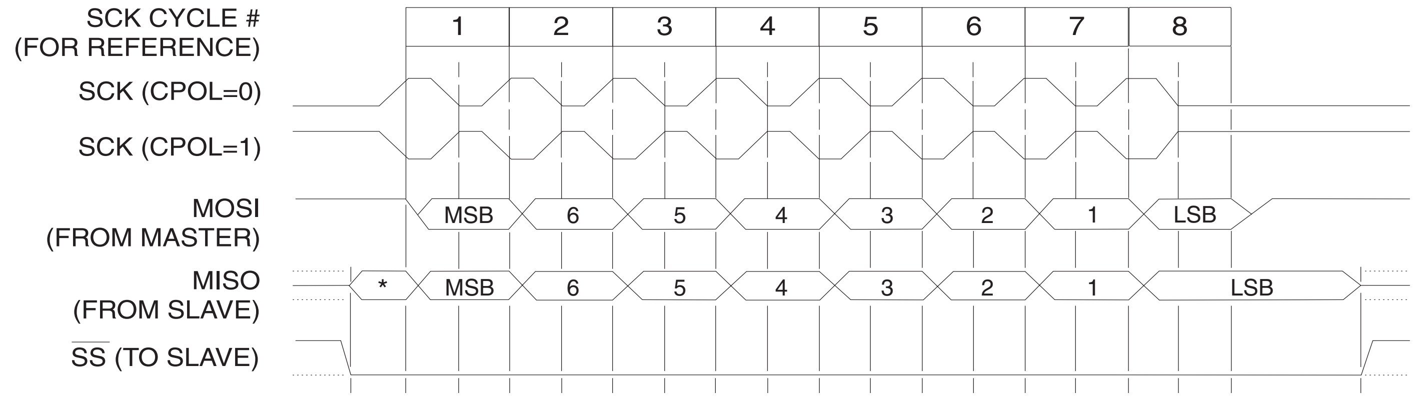


Figure 9. SPI Transfer Format with CPHA = 1



*Not defined but normally LSB of previously transmitted character

Interrupts

The AT89LS8252 has a total of six interrupt vectors: two external interrupts ($\overline{\text{INT0}}$ and $\overline{\text{INT1}}$), three timer interrupts (Timers 0, 1, and 2), and the serial port interrupt. These interrupts are all shown in Figure 10.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 10 shows that bit position IE.6 is unimplemented. In the AT89C51 and AT89LV51, bit position IE.5 is also unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

Timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register T2CON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and that bit will have to be cleared in software.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle. However, the Timer 2 flag, TF2, is set at S2P2 and is polled in the same cycle in which the timer overflows.

Table 10. Interrupt Enable (IE) Register

(MSB)(LSB)

EA	—	ET2	ES	ET1	EX1	ET0	EX0

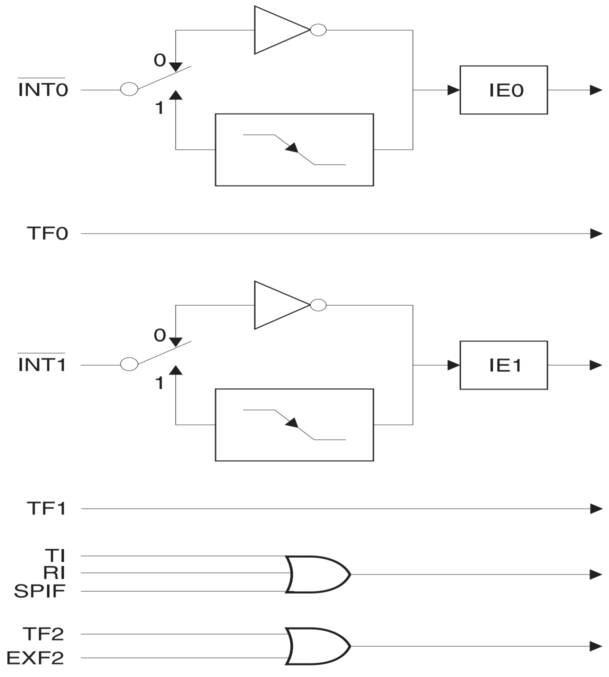
Enable Bit = 1 enables the interrupt.

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
—	IE.6	Reserved.
ET2	IE.5	Timer 2 interrupt enable bit.
ES	IE.4	SPI and UART interrupt enable bit.
ET1	IE.3	Timer 1 interrupt enable bit.
EX1	IE.2	External interrupt 1 enable bit.
ET0	IE.1	Timer 0 interrupt enable bit.
EX0	IE.0	External interrupt 0 enable bit.

User software should never write 1s to unimplemented bits, because they may be used in future AT89 products.

Figure 10. Interrupt Sources



7. To verify the byte just programmed, bring pin P2.7 to “L” and read the programmed data at pins P0.0 to P0.7.
8. Repeat steps 3 through 7 changing the address and data for the entire 2K or 8K bytes array or until the end of the object file is reached.
9. Power-off sequence:

   Set XTAL1 to “L”.

   Set RST and $\overline{\text{EA}}$ pins to “L”.

   Turn V_{CC} power off.

In the parallel programming mode, there is no auto-erase cycle and to reprogram any non-blank byte, the user needs to use the Chip Erase operation first to erase both arrays.

$\overline{\text{DATA}}$ Polling

The AT89LS8252 features $\overline{\text{DATA}}$ Polling to indicate the end of a write cycle. During a write cycle in the parallel or serial programming mode, an attempted read of the last byte written will result in the complement of the written datum on P0.7 (parallel mode), and on the MSB of the serial output byte on MISO (serial mode). Once the write cycle has been completed, true data are valid on all outputs, and the next cycle may begin. $\overline{\text{DATA}}$ Polling may begin any time after a write cycle has been initiated.

Ready/$\overline{\text{Busy}}$

The progress of byte programming in the parallel programming mode can also be monitored by the RDY/$\overline{\text{BSY}}$ output signal. Pin P3.4 is pulled Low after ALE goes High during programming to indicate $\overline{\text{BUSY}}$. P3.4 is pulled High again when programming is done to indicate READY.

Program Verify

If lock bits LB1 and LB2 have not been programmed, the programmed Code or Data byte can be read back via the address and data lines for verification. The state of the lock bits can also be verified directly in the parallel programming mode. In the serial programming mode, the state of the lock bits can only be verified indirectly by observing that the lock bit features are enabled.

Chip Erase

Both Flash and EEPROM arrays are erased electrically at the same time. In the parallel programming mode, chip erase is initiated by using the proper combination of control signals and by holding ALE/$\overline{\text{PROG}}$ low for 10 ms. The Code and Data arrays are written with all “1”s in the Chip Erase operation.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 16 ms.

During chip erase, a serial read from any address location will return 00H at the data outputs.

Serial Programming Fuse

A programmable fuse is available to disable Serial Programming if the user needs maximum system security. The Serial Programming Fuse can only be programmed or erased in the Parallel Programming Mode.

The AT89LS8252 is shipped with the Serial Programming Mode enabled.

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 030H and 031H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows:

(030H) = 1EH indicates manufactured by Atmel
(031H) = 82H indicates 89LS8252

Programming Interface

Every code byte in the Flash and EEPROM arrays can be written, and the entire array can be erased, by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

All major programming vendors offer worldwide support for the Atmel microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Serial Downloading

Both the Code and Data memory arrays can be programmed using the serial SPI bus while RST is pulled to V_{CC}. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before program/erase operations can be executed.

An auto-erase cycle is built into the self-timed programming operation (in the serial mode ONLY) and there is no need to first execute the Chip Erase instruction unless any of the lock bits have been programmed. The Chip Erase operation turns the content of every memory location in both the Code and Data arrays into FFH.

The Code and Data memory arrays have separate address spaces:

0000H to 1FFFH for Code memory and 000H to 7FFH for Data memory.

Either an external system clock is supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/40 of the crystal frequency. With a 12 MHz oscillator clock, the maximum SCK frequency is 300 kHz.

Serial Programming Algorithm

To program and verify the AT89LS8252 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:

   Apply power between V_{CC} and GND pins.

   Set RST pin to “H”.

   If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 12 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.
2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 40.
3. The Code or Data array is programmed one byte at a time by supplying the address and data together with the appropriate Write instruction. The selected memory location is first automatically erased before new data is written. The write cycle is self-timed and typically takes less than 2.5 ms at 5V and less than 10 ms at 2.7V.
4. Any memory location can be verified by using the Read instruction which returns the content at the selected address at serial output MISO/P1.6.
5. At the end of a programming session, RST can be set low to commence normal operation.

Power-off sequence (if needed):

Set XTAL1 to “L” (if a crystal is not used).

Set RST to “L”.

Turn V_{CC} power off.

Serial Programming Instruction

The Instruction Set for Serial Programming follows a 3-byte protocol and is shown in the following table:

Instruction Set

	Input Format			
Instruction	Byte 1	Byte 2	Byte 3	**Operation**
Programming Enable	1010 1100	0101 0011	xxxx xxxx	Enable serial programming interface after RST goes high.
Chip Erase	1010 1100	xxxx x100	xxxx xxxx	Chip erase both 8K & 2K memory arrays.
Read Code Memory	aaaa a001	low addr	xxxx xxxx	Read data from Code memory array at the selected address. The 5 MSBs of the first byte are the high order address bits. The low order address bits are in the second byte. Data are available at pin MISO during the third byte.
Write Code Memory	aaaa a010	low addr	data in	Write data to Code memory location at selected address. The address bits are the 5 MSBs of the first byte together with the second byte.
Read Data Memory	00aa a101	low addr	xxxx xxxx	Read data from Data memory array at selected address. Data are available at pin MISO during the third byte.
Write Data Memory	00aa a110	low addr	data in	Write data to Data memory location at selected address.
Write Lock Bits	1010 1100	LB1 LB2 LB3 x x111	xxxx xxxx	Write lock bits. Set LB1, LB2 or LB3 = “0” to program lock bits.

Notes: 1. $\overline{\text{DATA}}$ polling is used to indicate the end of a write cycle which typically takes less than 10 ms at 2.7V.
2. “aaaaa” = high order address.
3. “x” = don’t care.

Figure 14. Programming the Flash/EEPROM Memory

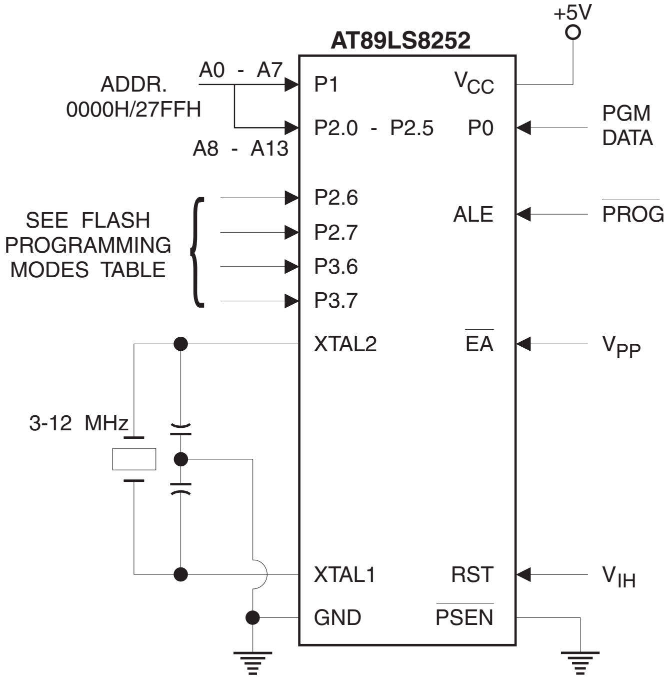


Figure 15. Flash/EEPROM Serial Downloading

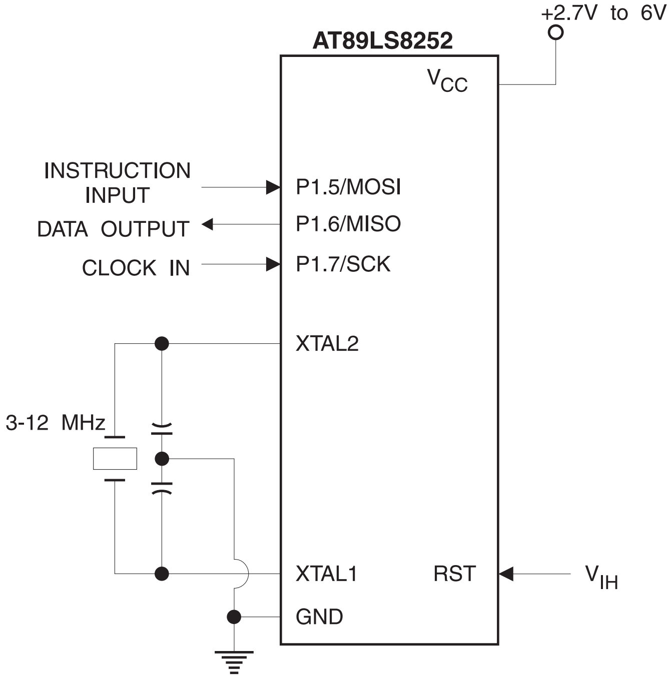
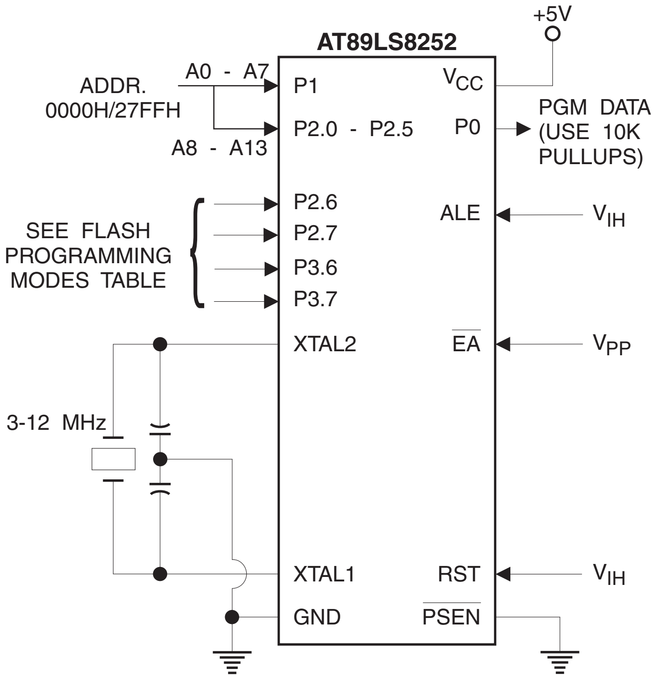


Figure 16. Verifying the Flash/EEPROM Memory



Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

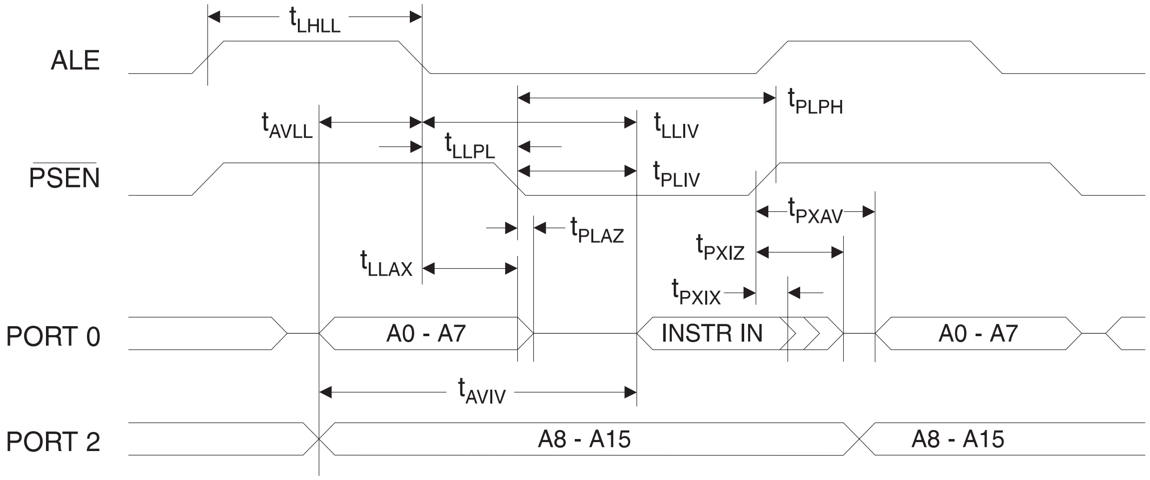
DC Characteristics

The values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 2.7V to 6.0V, unless otherwise noted.

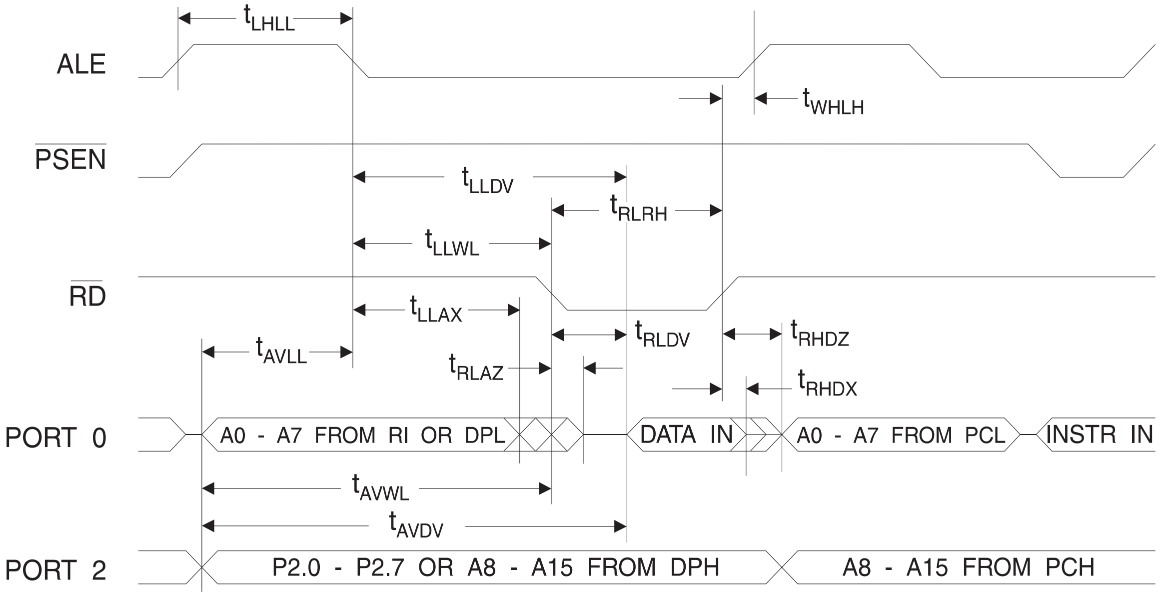
Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low Voltage	(Except $\overline{EA}$)	-0.5	0.2 V_{CC} - 0.1	V
V_{IL1}	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC} - 0.3	V
V_{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC} + 0.9	V_{CC} + 0.5	V
V_{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC} + 0.5	V
V_{OL}	Output Low Voltage (1) (Ports 1,2,3)	I_{OL} = 1.6 mA		0.5	V
V_{OL1}	Output Low Voltage (1) (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.5	V
V_{OH}	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 μA, V_{CC} = 5V ± 10%	2.4		V
		I_{OH} = -25 μA	0.75 V_{CC}		V
		I_{OH} = -10 μA	0.9 V_{CC}		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 μA, V_{CC} = 5V ± 10%	2.4		V
		I_{OH} = -300 μA	0.75 V_{CC}		V
		I_{OH} = -80 μA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	μA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V		-650	μA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	μA
RRST	Reset Pulldown Resistor		50	300	KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz		25	mA
		Idle Mode, 12 MHz		6.5	mA
	Power Down Mode (2)	V_{CC} = 6V		100	μA
		V_{CC} = 3V		40	μA

Notes:
1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA
   Ports 1,2, 3: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power Down is 2V

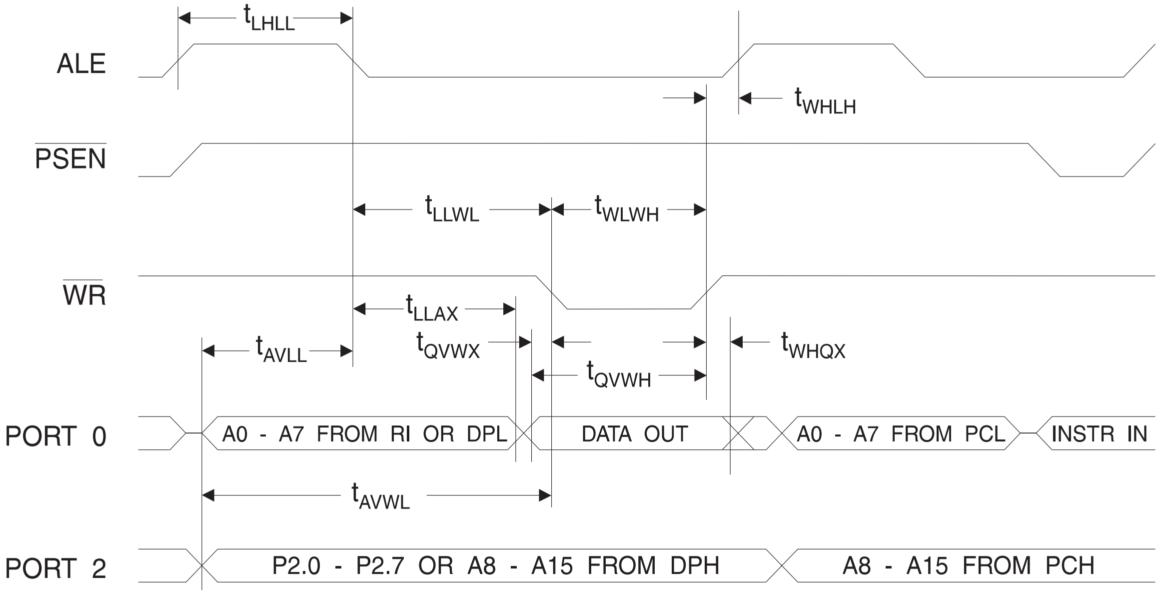
External Program Memory Read Cycle



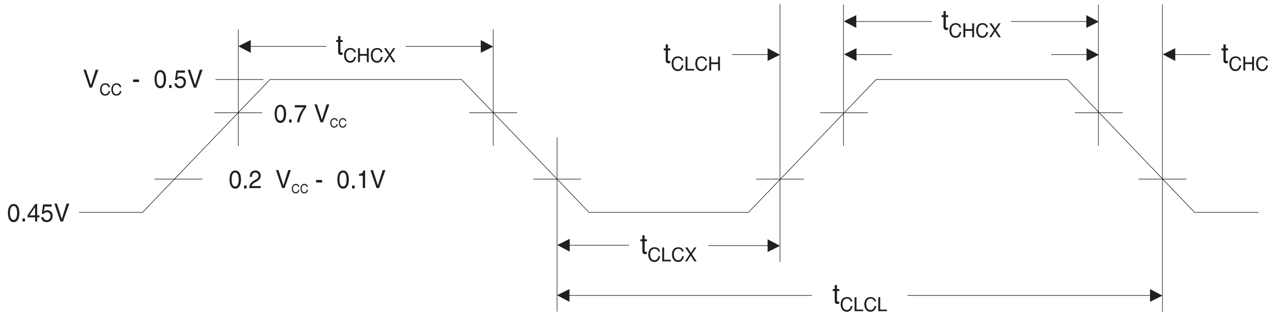
External Data Memory Read Cycle



External Data Memory Write Cycle



External Clock Drive Waveforms

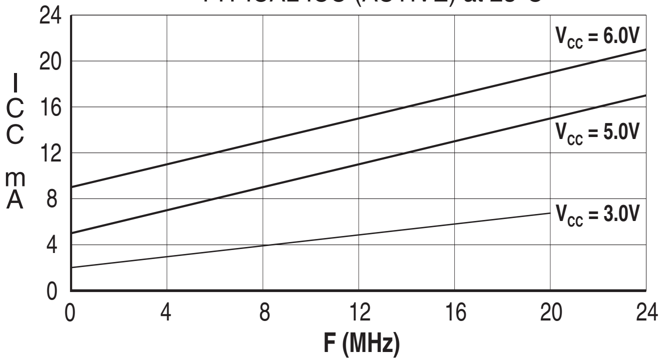


External Clock Drive

Symbol	Parameter	V_{CC} = 2.7V to 6.0V		Units
		Min	Max	
$1/t_{CLCL}$	Oscillator Frequency	0	12	MHz
t_{CLCL}	Clock Period	83.3		ns
t_{CHCX}	High Time	30		ns
t_{CLCX}	Low Time	30		ns
t_{CLCH}	Rise Time		20	ns
t_{CHCL}	Fall Time		20	ns

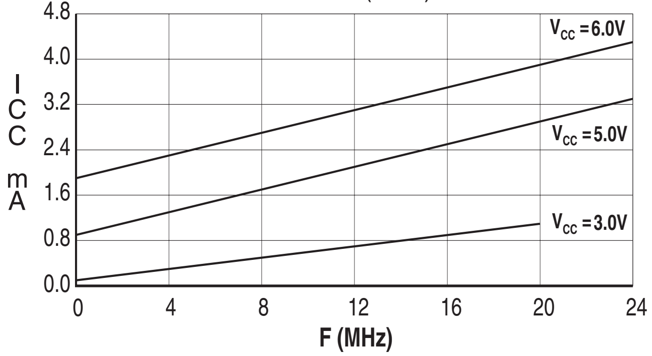
AT89LS8252

TYPICAL ICC (ACTIVE) at 25°C



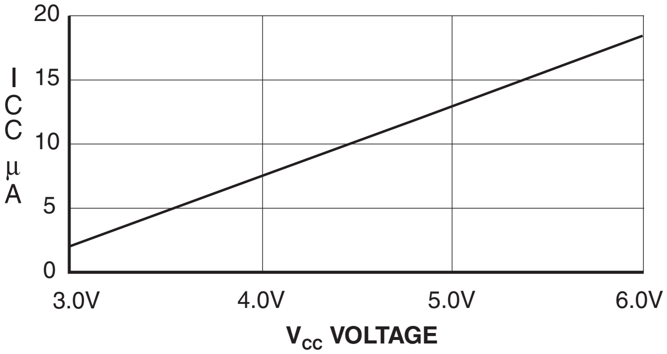
AT89LS8252

TYPICAL ICC (IDLE) at 25°C



AT89LS8252

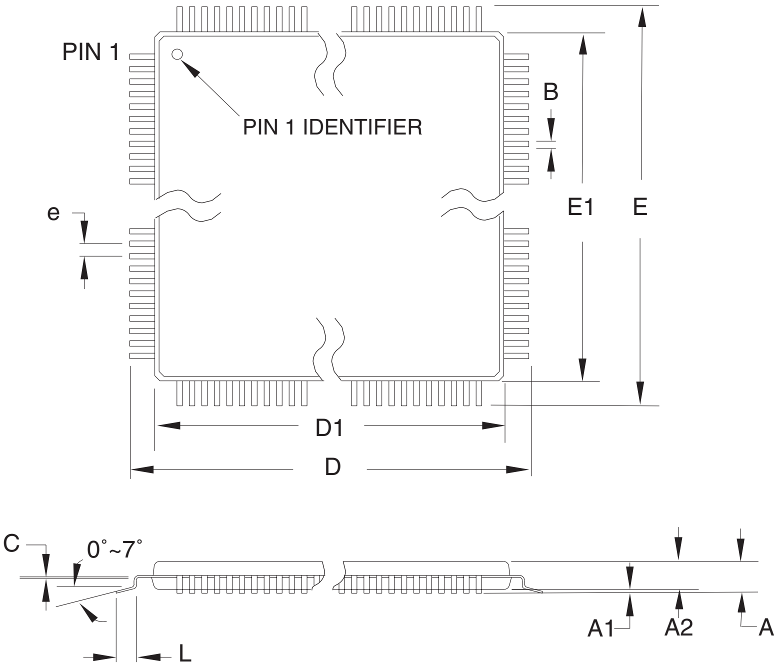
TYPICAL ICC vs. VOLTAGE - POWER DOWN (85°C)



Notes:
1. XTAL1 tied to GND for I_{CC} (power down)
2. Lock bits programmed

Packaging Information

44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

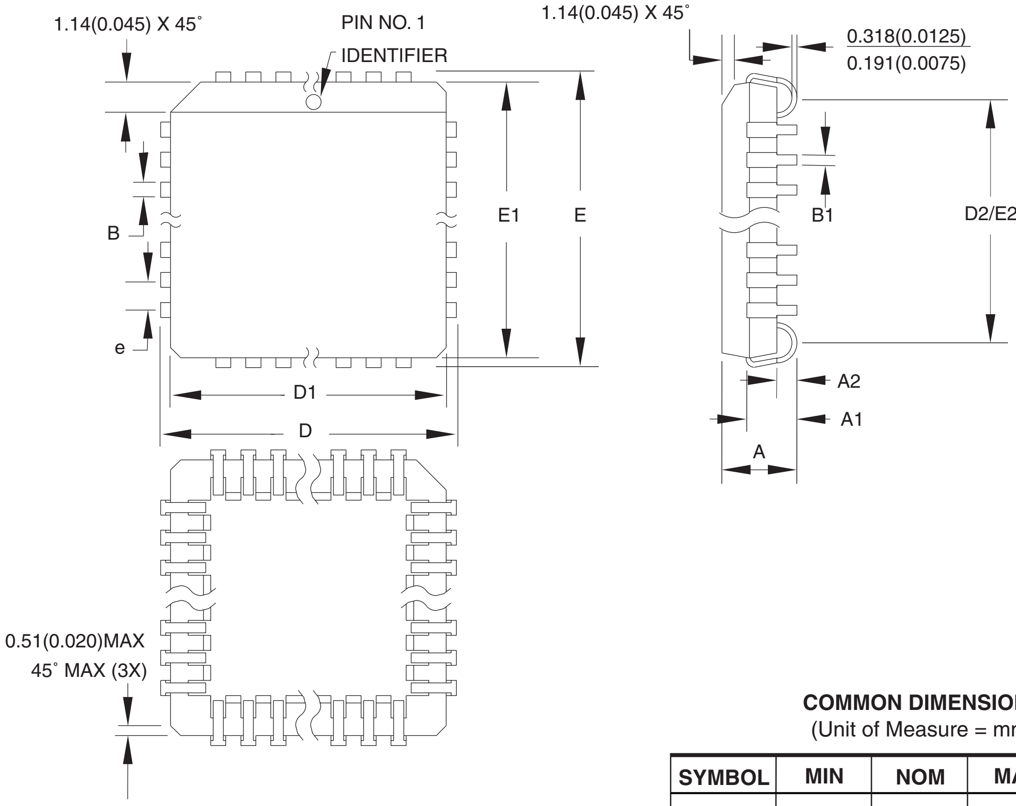
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

2325 Orchard Parkway San Jose, CA 95131	**TITLE** **44A,** 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	**DRAWING NO.** 44A	**REV.** B

44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

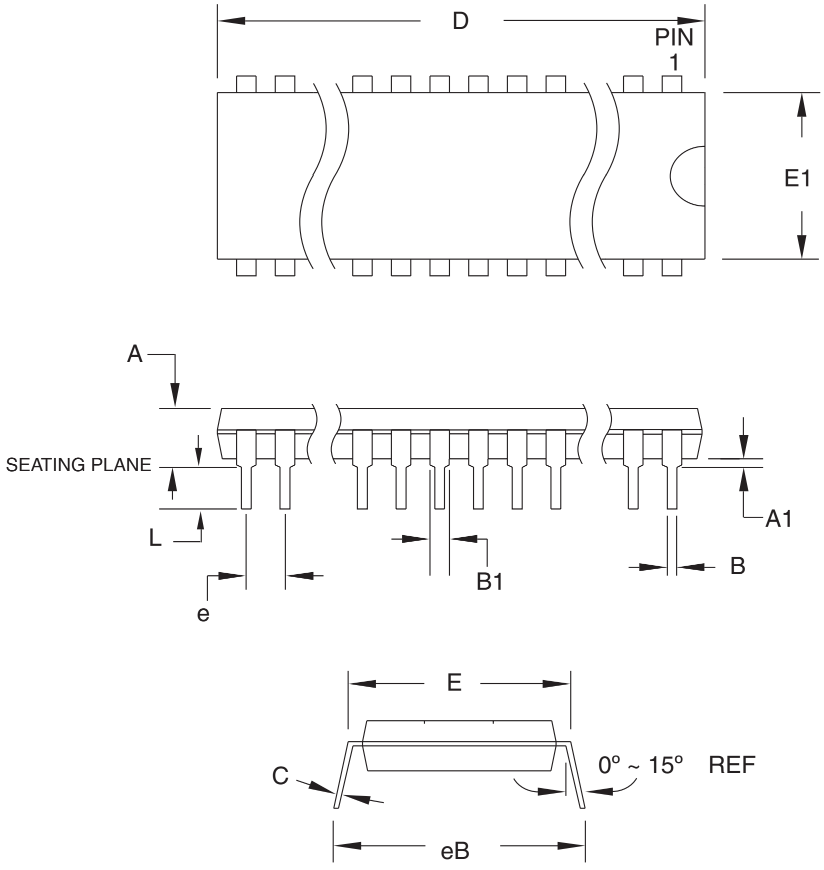
SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B

40P6 – PDIP



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	4.826	
A1	0.381	–	–	
D	52.070	–	52.578	Note 2
E	15.240	–	15.875	
E1	13.462	–	13.970	Note 2
B	0.356	–	0.559	
B1	1.041	–	1.651	
L	3.048	–	3.556	
C	0.203	–	0.381	
eB	15.494	–	17.526	
e	2.540 TYP			

Notes:
1. This package conforms to JEDEC reference MS-011, Variation AC.
2. Dimensions D and E1 do not include mold Flash or Protrusion. Mold Flash or Protrusion shall not exceed 0.25 mm (0.010").

09/28/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**40P6**, 40-lead (0.600"/15.24 mm Wide) Plastic Dual Inline Package (PDIP)	40P6	B

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